



Material Content Data Sheet



Sales Product Name		SAK-XC164CM-16F20F BA		Issued		25. September 2017		
MA#		MA000789522						
Package		PG-LQFP-64-4		Weight*		379.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.143	5.04	5.04	50383	50383
leadframe	non noble metal	magnesium	7439-95-4	0.179	0.05		471	
	inorganic material	silicon	7440-21-3	0.775	0.20		2040	
	non noble metal	nickel	7440-02-0	3.578	0.94		9418	
	non noble metal	copper	7440-50-8	114.739	30.20	31.39	301992	313921
wire	noble metal	gold	7440-57-5	1.871	0.49	0.49	4925	4925
encapsulation	organic material	carbon black	1333-86-4	1.148	0.30		3023	
	plastics	epoxy resin	-	31.008	8.16		81614	
	inorganic material	silicondioxide	60676-86-0	197.535	52.00	60.46	519912	604549
leadfinish	non noble metal	tin	7440-31-5	4.118	1.08	1.08	10838	10838
plating	noble metal	silver	7440-22-4	1.710	0.45	0.45	4502	4502
glue	plastics	epoxy resin	-	0.827	0.22		2176	
	noble metal	silver	7440-22-4	3.308	0.87	1.09	8706	10882
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com